

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPP70N04S4-06	**Issued**	08. April 2022
MA#	MA005710649		
Package	PG-TO220-3-1	**Weight***	2034.35 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.373	0.07	0.07	675	675
leadframe	inorganic material	phosphorus	7723-14-0	0.245	0.01		120	
	non noble metal	iron	7439-89-6	0.816	0.04		401	
	non noble metal	copper	7440-50-8	815.335	40.08	40.13	400784	401305
wire	non noble metal	aluminium	7429-90-5	4.541	0.22	0.22	2232	2232
encapsulation	inorganic material	zincoxide	1314-13-2	5.986	0.29		2942	
	miscellaneous	miscellaneous	-	23.943	1.18		11769	
	plastics	epoxy resin	-	89.786	4.41		44135	
	inorganic material	silicondioxide	60676-86-0	478.859	23.54	29.42	235388	294234
leadfinish	non noble metal	tin	7440-31-5	21.462	1.06	1.06	10550	10550
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.244	0.01	0.01	120	121
solder	non noble metal	tin	7440-31-5	0.030			15	
	noble metal	silver	7440-22-4	0.038			19	
	non noble metal	lead	7439-92-1	1.453	0.07	0.07	714	748
heatspreader	inorganic material	phosphorus	7723-14-0	0.177	0.01		87	
	non noble metal	iron	7439-89-6	0.590	0.03		290	
	non noble metal	copper	7440-50-8	589.466	28.98	29.02	289758	290135
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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